

Welcome to [E-XFL.COM](#)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Discontinued at Digi-Key
Core Processor	RL78
Core Size	16-Bit
Speed	32MHz
Connectivity	CSI, I ² C, LINbus, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	31
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	2.5K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 10x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LQFP
Supplier Device Package	44-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f104fadfp-30

(2/5)

Pin count	Package	Fields of Application Note	Ordering Part Number
40 pins	40-pin plastic HWQFN (6 × 6 mm, 0.5 mm pitch)	A	R5F104EAANA#U0, R5F104ECANA#U0, R5F104EDANA#U0, R5F104EEANA#U0, R5F104EFANA#U0, R5F104EGANA#U0, R5F104EHANA#U0 R5F104EAANA#W0, R5F104ECANA#W0, R5F104EDANA#W0, R5F104EEANA#W0, R5F104EFANA#W0, R5F104EGANA#W0, R5F104EHANA#W0
		D	R5F104EADNA#U0, R5F104ECDNA#U0, R5F104EDDNA#U0, R5F104EEDNA#U0, R5F104EFDNA#U0, R5F104EGDNA#U0, R5F104EHDNA#U0 R5F104EADNA#W0, R5F104ECDNA#W0, R5F104EDDNA#W0, R5F104EEDNA#W0, R5F104EFDNA#W0, R5F104EGDNA#W0, R5F104EHDNA#W0
		G	R5F104EAGNA#U0, R5F104ECGNA#U0, R5F104EDGNA#U0, R5F104EEGNA#U0, R5F104EFGNA#U0, R5F104EGGNA#U0, R5F104EHGNA#U0 R5F104EAGNA#W0, R5F104ECGNA#W0, R5F104EDGNA#W0, R5F104EEGNA#W0, R5F104EFGNA#W0, R5F104EGGNA#W0, R5F104EHGNA#W0
44 pins	44-pin plastic LQFP (10 × 10, 0.8 mm pitch)	A	R5F104FAAFP#V0, R5F104FC AFP#V0, R5F104FDAFP#V0, R5F104FEA FP#V0, R5F104FFA FP#V0, R5F104FG AFP#V0, R5F104FH AFP#V0, R5F104FJA FP#V0 R5F104FAAFP#X0, R5F104FC AFP#X0, R5F104FDAFP#X0, R5F104FEA FP#X0, R5F104FFA FP#X0, R5F104FG AFP#X0, R5F104FH AFP#X0, R5F104FJA FP#X0
		D	R5F104FADFP#V0, R5F104FCDFP#V0, R5F104FDDFP#V0, R5F104FEDFP#V0, R5F104FFDFP#V0, R5F104FGDFP#V0, R5F104FHDFP#V0, R5F104FJD FP#V0 R5F104FADFP#X0, R5F104FCDFP#X0, R5F104FDDFP#X0, R5F104FEDFP#X0, R5F104FFDFP#X0, R5F104FGDFP#X0, R5F104FHDFP#X0, R5F104FJD FP#X0
		G	R5F104FAGFP#V0, R5F104FC GFP#V0, R5F104FD GFP#V0, R5F104FEGFP#V0, R5F104FF GFP#V0, R5F104FG GFP#V0, R5F104FH GFP#V0, R5F104FJ GFP#V0 R5F104FAGFP#X0, R5F104FC GFP#X0, R5F104FD GFP#X0, R5F104FEGFP#X0, R5F104FF GFP#X0, R5F104FG GFP#X0, R5F104FH GFP#X0, R5F104FJ GFP#X0

Note For the fields of application, refer to **Figure 1 - 1 Part Number, Memory Size, and Package of RL78/G14**.

Caution The ordering part numbers represent the numbers at the time of publication. For the latest ordering part numbers, refer to the target product page of the Renesas Electronics website.

(4/5)

Pin count	Package	Fields of Application Note	Ordering Part Number
64 pins	64-pin plastic LQFP (12 × 12 mm, 0.65 mm pitch)	A	R5F104LCAFA#V0, R5F104LDAFA#V0, R5F104LEAFA#V0, R5F104LFAFA#V0, R5F104LGAF#V0, R5F104LHAF#V0, R5F104LJAFA#V0 R5F104LCAFA#X0, R5F104LDAFA#X0, R5F104LEAFA#X0, R5F104LFAFA#X0, R5F104LGAF#X0, R5F104LHAF#X0, R5F104LJAFA#X0 R5F104LKAF#30, R5F104LLAF#30 R5F104LKAF#50, R5F104LLAF#50
		D	R5F104LCDFA#V0, R5F104LDDFA#V0, R5F104LEDFA#V0, R5F104LFDF#V0, R5F104LGDF#V0, R5F104LHDFA#V0, R5F104LJDFA#V0 R5F104LCDFA#X0, R5F104LDDFA#X0, R5F104LEDFA#X0, R5F104LFDF#X0, R5F104LGDF#X0, R5F104LHDFA#X0, R5F104LJDFA#X0
		G	R5F104LCGFA#V0, R5F104LDGFA#V0, R5F104LEGFA#V0, R5F104LFGFA#V0, R5F104LGGFA#V0, R5F104LHGFA#V0, R5F104LJGFA#V0 R5F104LCGFA#X0, R5F104LDGFA#X0, R5F104LEGFA#X0, R5F104LFGFA#X0, R5F104LGGFA#X0, R5F104LHGFA#X0, R5F104LJGFA#X0 R5F104LKGF#30, R5F104LLGF#30 R5F104LKGF#50, R5F104LLGF#50
	64-pin plastic LFQFP (10 × 10 mm, 0.5 mm pitch)	A	R5F104LCAFB#V0, R5F104LDAFB#V0, R5F104LEAFB#V0, R5F104LFAFB#V0, R5F104LGAFB#V0, R5F104LHAFB#V0, R5F104LJAFB#V0 R5F104LCAFB#X0, R5F104LDAFB#X0, R5F104LEAFB#X0, R5F104LFAFB#X0, R5F104LGAFB#X0, R5F104LHAFB#X0, R5F104LJAFB#X0 R5F104LKAFB#30, R5F104LLAFB#30 R5F104LKAFB#50, R5F104LLAFB#50
		D	R5F104LCDFB#V0, R5F104LDDFB#V0, R5F104LEDFB#V0, R5F104LFDFB#V0, R5F104LGDFB#V0, R5F104LHDFB#V0, R5F104LJDFB#V0 R5F104LCDFB#X0, R5F104LDDFB#X0, R5F104LEDFB#X0, R5F104LFDFB#X0, R5F104LGDFB#X0, R5F104LHDFB#X0, R5F104LJDFB#X0
		G	R5F104LCGFB#V0, R5F104LDGFB#V0, R5F104LEGFB#V0, R5F104LFGFB#V0, R5F104LGGFB#V0, R5F104LHGFB#V0, R5F104LJGFB#V0 R5F104LCGFB#X0, R5F104LDGFB#X0, R5F104LEGFB#X0, R5F104LFGFB#X0, R5F104LGGFB#X0, R5F104LHGFB#X0, R5F104LJGFB#X0 R5F104LKGF#30, R5F104LLGF#30 R5F104LKGF#50, R5F104LLGF#50
	64-pin plastic FLGA (5 × 5 mm, 0.5 mm pitch)	A	R5F104LCALA#U0, R5F104LDALA#U0, R5F104LEALA#U0, R5F104LFALA#U0, R5F104LGALA#U0, R5F104LHALA#U0, R5F104LJALA#U0 R5F104LCALA#W0, R5F104LDALA#W0, R5F104LEALA#W0, R5F104LFALA#W0, R5F104LGALA#W0, R5F104LHALA#W0, R5F104LJALA#W0 R5F104LKALA#U0, R5F104LLALA#U0 R5F104LKALA#W0, R5F104LLALA#W0
		G	R5F104LCGLA#U0, R5F104LDGLA#U0, R5F104LEGLA#U0, R5F104LFGLA#U0, R5F104LGGLA#U0, R5F104LHGLA#U0, R5F104LJGLA#U0, R5F104LKGLA#U0, R5F104LLGLA#U0 R5F104LCGLA#W0, R5F104LDGLA#W0, R5F104LEGLA#W0, R5F104LFGLA#W0, R5F104LGGLA#W0, R5F104LHGLA#W0, R5F104LJGLA#W0, R5F104LKGLA#W0, R5F104LLGLA#W0
	64-pin plastic LQFP (14 × 14 mm, 0.8 mm pitch)	A	R5F104LCAP#V0, R5F104LDAFP#V0, R5F104LEAfp#V0, R5F104LFAFP#V0, R5F104LGAFP#V0, R5F104LHAFP#V0, R5F104LJAfp#V0 R5F104LCAP#X0, R5F104LDAFP#X0, R5F104LEAfp#X0, R5F104LFAFP#X0, R5F104LGAFP#X0, R5F104LHAFP#X0, R5F104LJAfp#X0
		D	R5F104LCDFP#V0, R5F104LDDFP#V0, R5F104LEDFP#V0, R5F104LFDFP#V0, R5F104LGDFP#V0, R5F104LHDFP#V0, R5F104LJDFP#V0 R5F104LCDFP#X0, R5F104LDDFP#X0, R5F104LEDFP#X0, R5F104LFDFP#X0, R5F104LGDFP#X0, R5F104LHDFP#X0, R5F104LJDFP#X0
		G	R5F104LCGFP#V0, R5F104LDGFP#V0, R5F104LEGFP#V0, R5F104LFGFP#V0, R5F104LGGFP#V0, R5F104LHGFP#V0, R5F104LJGFP#V0 R5F104LCGFP#X0, R5F104LDGFP#X0, R5F104LEGFP#X0, R5F104LFGFP#X0, R5F104LGGFP#X0, R5F104LHGFP#X0, R5F104LJGFP#X0

Note For the fields of application, refer to **Figure 1 - 1 Part Number, Memory Size, and Package of RL78/G14**.

Caution The ordering part numbers represent the numbers at the time of publication. For the latest ordering part numbers, refer to the target product page of the Renesas Electronics website.

(2/2)

Item	30-pin	32-pin	36-pin	40-pin				
	R5F104Ax (x = A, C to E)	R5F104Bx (x = A, C to E)	R5F104Cx (x = A, C to E)	R5F104Ex (x = A, C to E)				
Clock output/buzzer output	2	2	2	2				
[30-pin, 32-pin, 36-pin products]								
• 2.44 kHz, 4.88 kHz, 9.76 kHz, 1.25 MHz, 2.5 MHz, 5 MHz, 10 MHz (Main system clock: f _{MAIN} = 20 MHz operation)								
[40-pin products]								
• 2.44 kHz, 4.88 kHz, 9.76 kHz, 1.25 MHz, 2.5 MHz, 5 MHz, 10 MHz (Main system clock: f _{MAIN} = 20 MHz operation)								
• 256 Hz, 512 Hz, 1,024 kHz, 2,048 kHz, 4,096 kHz, 8,192 kHz, 16,384 kHz, 32,768 kHz (Subsystem clock: f _{SUB} = 32.768 kHz operation)								
8/10-bit resolution A/D converter	8 channels	8 channels	8 channels	9 channels				
Serial interface	[30-pin, 32-pin products]							
• CSI: 1 channel/UART (UART supporting LIN-bus): 1 channel/simplified I ² C: 1 channel								
• CSI: 1 channel/UART: 1 channel/simplified I ² C: 1 channel								
• CSI: 1 channel/UART: 1 channel/simplified I ² C: 1 channel								
[36-pin, 40-pin products]								
• CSI: 1 channel/UART (UART supporting LIN-bus): 1 channel/simplified I ² C: 1 channel								
• CSI: 1 channel/UART: 1 channel/simplified I ² C: 1 channel								
• CSI: 2 channels/UART: 1 channel/simplified I ² C: 2 channels								
I ² C bus	1 channel	1 channel	1 channel	1 channel				
Data transfer controller (DTC)	28 sources				29 sources			
Event link controller (ELC)	Event input: 19 Event trigger output: 7				Event input: 20 Event trigger output: 7			
Vectorized interrupt sources	Internal	24	24	24	24			
	External	6	6	6	7			
Key interrupt	—	—	—	—	4			
Reset	<ul style="list-style-type: none"> • Reset by RESET pin • Internal reset by watchdog timer • Internal reset by power-on-reset • Internal reset by voltage detector • Internal reset by illegal instruction execution <small>Note</small> • Internal reset by RAM parity error • Internal reset by illegal-memory access 							
Power-on-reset circuit	<ul style="list-style-type: none"> • Power-on-reset: 1.51 ±0.04 V (T_A = -40 to +85°C) 1.51 ±0.06 V (T_A = -40 to +105°C) • Power-down-reset: 1.50 ±0.04 V (T_A = -40 to +85°C) 1.50 ±0.06 V (T_A = -40 to +105°C) 							
Voltage detector	1.63 V to 4.06 V (14 stages)							
On-chip debug function	Provided							
Power supply voltage	V _{DD} = 1.6 to 5.5 V (T _A = -40 to +85°C) V _{DD} = 2.4 to 5.5 V (T _A = -40 to +105°C)							
Operating ambient temperature	T _A = -40 to +85°C (A: Consumer applications, D: Industrial applications), T _A = -40 to +105°C (G: Industrial applications)							

Note

The illegal instruction is generated when instruction code FFH is executed.

Reset by the illegal instruction execution not is issued by emulation with the in-circuit emulator or on-chip debug emulator.

- Note** The flash library uses RAM in self-programming and rewriting of the data flash memory.
The target products and start address of the RAM areas used by the flash library are shown below.
R5F104xJ (x = F, G, J, L, M, P): Start address F9F00H
For the RAM areas used by the flash library, see **Self RAM list of Flash Self-Programming Library for RL78 Family (R20UT2944)**.

[80-pin, 100-pin products (code flash memory 96 KB to 256 KB)]

Caution This outline describes the functions at the time when Peripheral I/O redirection register 0, 1 (PIOR0, 1) are set to 00H.

(1/2)

Item	80-pin	100-pin	
	R5F104Mx (x = F to H, J)	R5F104Px (x = F to H, J)	
Code flash memory (KB)	96 to 256	96 to 256	
Data flash memory (KB)	8	8	
RAM (KB)	12 to 24 Note	12 to 24 Note	
Address space	1 MB		
Main system clock	High-speed system clock X1 (crystal/ceramic) oscillation, external main system clock input (EXCLK) HS (high-speed main) mode: 1 to 20 MHz ($V_{DD} = 2.7$ to 5.5 V), HS (high-speed main) mode: 1 to 16 MHz ($V_{DD} = 2.4$ to 5.5 V), LS (low-speed main) mode: 1 to 8 MHz ($V_{DD} = 1.8$ to 5.5 V), LV (low-voltage main) mode: 1 to 4 MHz ($V_{DD} = 1.6$ to 5.5 V)		
	High-speed on-chip oscillator clock (f_{IH}) HS (high-speed main) mode: 1 to 32 MHz ($V_{DD} = 2.7$ to 5.5 V), HS (high-speed main) mode: 1 to 16 MHz ($V_{DD} = 2.4$ to 5.5 V), LS (low-speed main) mode: 1 to 8 MHz ($V_{DD} = 1.8$ to 5.5 V), LV (low-voltage main) mode: 1 to 4 MHz ($V_{DD} = 1.6$ to 5.5 V)		
Subsystem clock	XT1 (crystal) oscillation, external subsystem clock input (EXCLKS) 32.768 kHz		
Low-speed on-chip oscillator clock	15 kHz (TYP.): $V_{DD} = 1.6$ to 5.5 V		
General-purpose register	8 bits × 32 registers (8 bits × 8 registers × 4 banks)		
Minimum instruction execution time	0.03125 µs (High-speed on-chip oscillator clock: $f_{IH} = 32$ MHz operation) 0.05 µs (High-speed system clock: $f_{MX} = 20$ MHz operation) 30.5 µs (Subsystem clock: $f_{SUB} = 32.768$ kHz operation)		
Instruction set	<ul style="list-style-type: none"> • Data transfer (8/16 bits) • Adder and subtractor/logical operation (8/16 bits) • Multiplication (8 bits × 8 bits, 16 bits × 16 bits), Division (16 bits ÷ 16 bits, 32 bits ÷ 32 bits) • Multiplication and Accumulation (16 bits × 16 bits + 32 bits) • Rotate, barrel shift, and bit manipulation (Set, reset, test, and Boolean operation), etc. 		
I/O port	Total CMOS I/O CMOS input CMOS output N-ch open-drain I/O (6 V tolerance)	74 64 5 1 4	92 82 5 1 4
Timer	16-bit timer Watchdog timer Real-time clock (RTC) 12-bit interval timer Timer output RTC output	12 channels (TAU: 8 channels, Timer RJ: 1 channel, Timer RD: 2 channels, Timer RG: 1 channel) 1 channel 1 channel 1 channel Timer outputs: 18 channels PWM outputs: 12 channels 1 • 1 Hz (subsystem clock: $f_{SUB} = 32.768$ kHz)	

Note In the case of the 24 KB, this is about 23 KB when the self-programming function and data flash function are used (For details, see **CHAPTER 3** in the RL78/G14 User's Manual).

(TA = -40 to +85°C, 1.6 V ≤ EV_{DD0} = EV_{DD1} ≤ V_{DD} ≤ 5.5 V, V_{SS} = EV_{SS0} = EV_{SS1} = 0 V) (3/5)

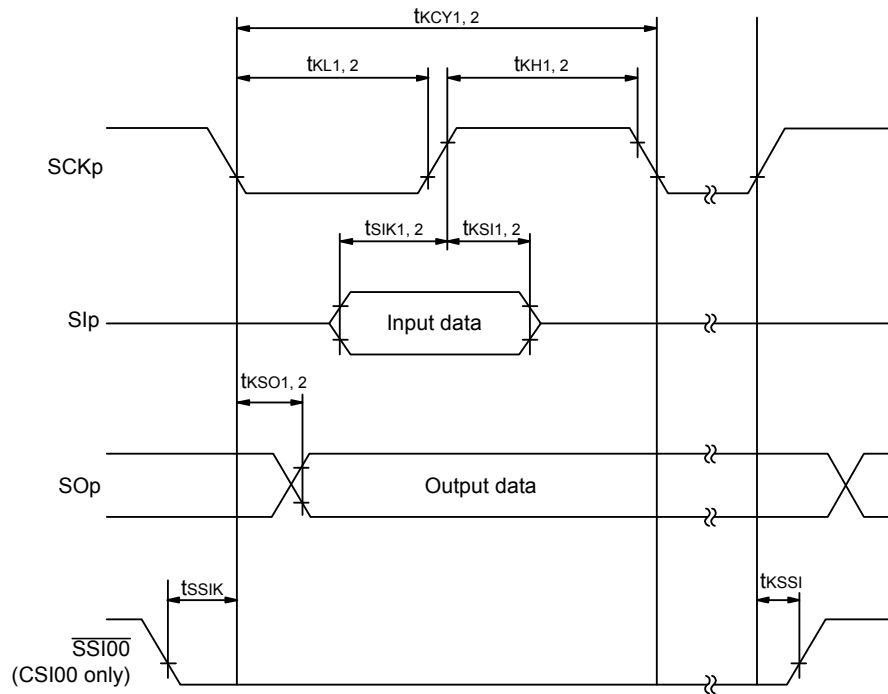
Items	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Input voltage, high	V _{IH1}	P00 to P06, P10 to P17, P30, P31, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P100 to P102, P110, P111, P120, P140 to P147	Normal input buffer	0.8 EV _{DD0}		EV _{DD0}	V
	V _{IH2}	P01, P03, P04, P10, P14 to P17, P30, P43, P44, P50, P53 to P55, P80, P81, P142, P143	TTL input buffer 4.0 V ≤ EV _{DD0} ≤ 5.5 V	2.2		EV _{DD0}	V
			TTL input buffer 3.3 V ≤ EV _{DD0} < 4.0 V	2.0		EV _{DD0}	V
			TTL input buffer 1.6 V ≤ EV _{DD0} < 3.3 V	1.5		EV _{DD0}	V
	V _{IH3}	P20 to P27, P150 to P156		0.7 V _{DD}		V _{DD}	V
	V _{IH4}	P60 to P63		0.7 EV _{DD0}		6.0	V
Input voltage, low	V _{IL1}	P00 to P06, P10 to P17, P30, P31, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P100 to P102, P110, P111, P120, P140 to P147	Normal input buffer	0		0.2 EV _{DD0}	V
	V _{IL2}	P01, P03, P04, P10, P14 to P17, P30, P43, P44, P50, P53 to P55, P80, P81, P142, P143	TTL input buffer 4.0 V ≤ EV _{DD0} ≤ 5.5 V	0		0.8	V
			TTL input buffer 3.3 V ≤ EV _{DD0} < 4.0 V	0		0.5	V
			TTL input buffer 1.6 V ≤ EV _{DD0} < 3.3 V	0		0.32	V
	V _{IL3}	P20 to P27, P150 to P156		0		0.3 V _{DD}	V
	V _{IL4}	P60 to P63		0		0.3 EV _{DD0}	V
	V _{IL5}	P121 to P124, P137, EXCLK, EXCLKS, RESET		0		0.2 V _{DD}	V

Caution The maximum value of V_{IH} of pins P00, P02 to P04, P10, P11, P13 to P15, P17, P30, P43 to P45, P50 to P55, P71, P74, P80 to P82, and P142 to P144 is EV_{DD0}, even in the N-ch open-drain mode.

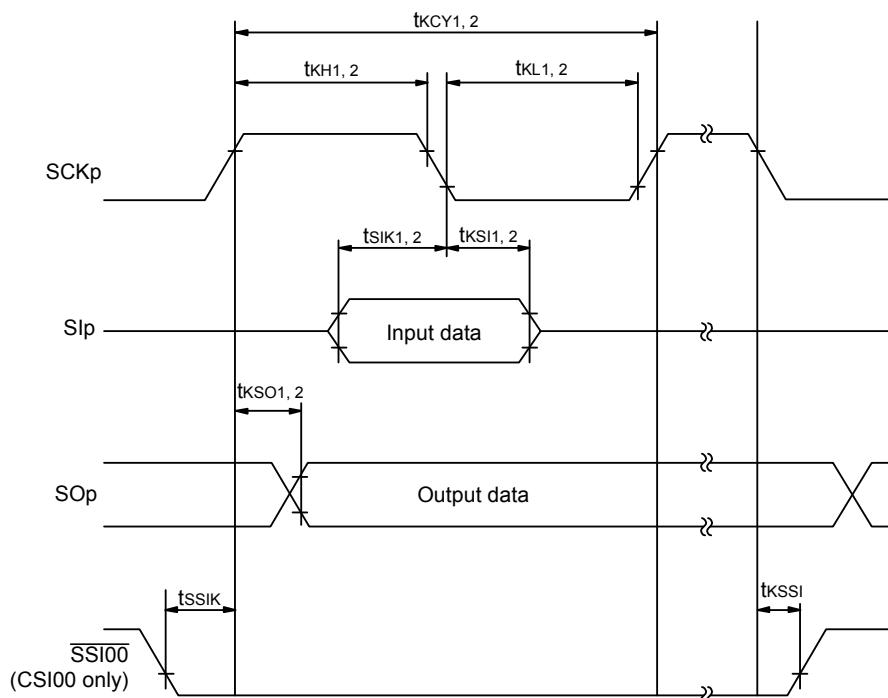
Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

CSI mode serial transfer timing (during communication at same potential)

(When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)

**CSI mode serial transfer timing (during communication at same potential)**

(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)

**Remark 1.** p: CSI number (p = 00, 01, 10, 11, 20, 21, 30, 31)**Remark 2.** m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13)

(6) Communication at different potential (1.8 V, 2.5 V, 3 V) (UART mode)(TA = -40 to +85°C, 1.6 V ≤ EV_{D0} = EV_{D1} ≤ V_{DD} ≤ 5.5 V, V_{SS} = EV_{S0} = EV_{S1} = 0 V)

Parameter	Symbol	Conditions	HS (high-speed main) mode		LS (low-speed main) mode		LV (low-voltage main) mode		Unit
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Transfer rate		reception	4.0 V ≤ EV _{D0} ≤ 5.5 V, 2.7 V ≤ V _b ≤ 4.0 V		f _{MCK} /6 Note 1		f _{MCK} /6 Note 1		f _{MCK} /6 Note 1 bps
			Theoretical value of the maximum transfer rate f _{MCK} = f _{CLK} Note 4		5.3		1.3		0.6 Mbps
			2.7 V ≤ EV _{D0} < 4.0 V, 2.3 V ≤ V _b ≤ 2.7 V		f _{MCK} /6 Note 1		f _{MCK} /6 Note 1		f _{MCK} /6 Note 1 bps
			Theoretical value of the maximum transfer rate f _{MCK} = f _{CLK} Note 4		5.3		1.3		0.6 Mbps
			1.8 V ≤ EV _{D0} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V		f _{MCK} /6 Notes 1, 2, 3		f _{MCK} /6 Notes 1, 2		f _{MCK} /6 Notes 1, 2 bps
			Theoretical value of the maximum transfer rate f _{MCK} = f _{CLK} Note 4		5.3		1.3		0.6 Mbps

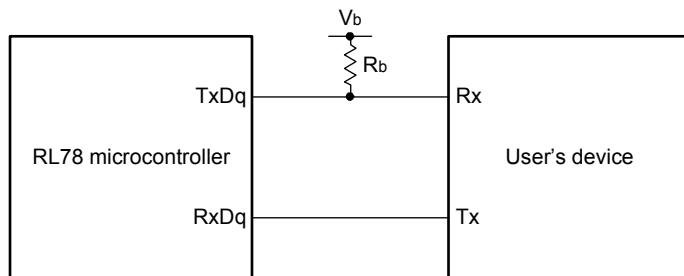
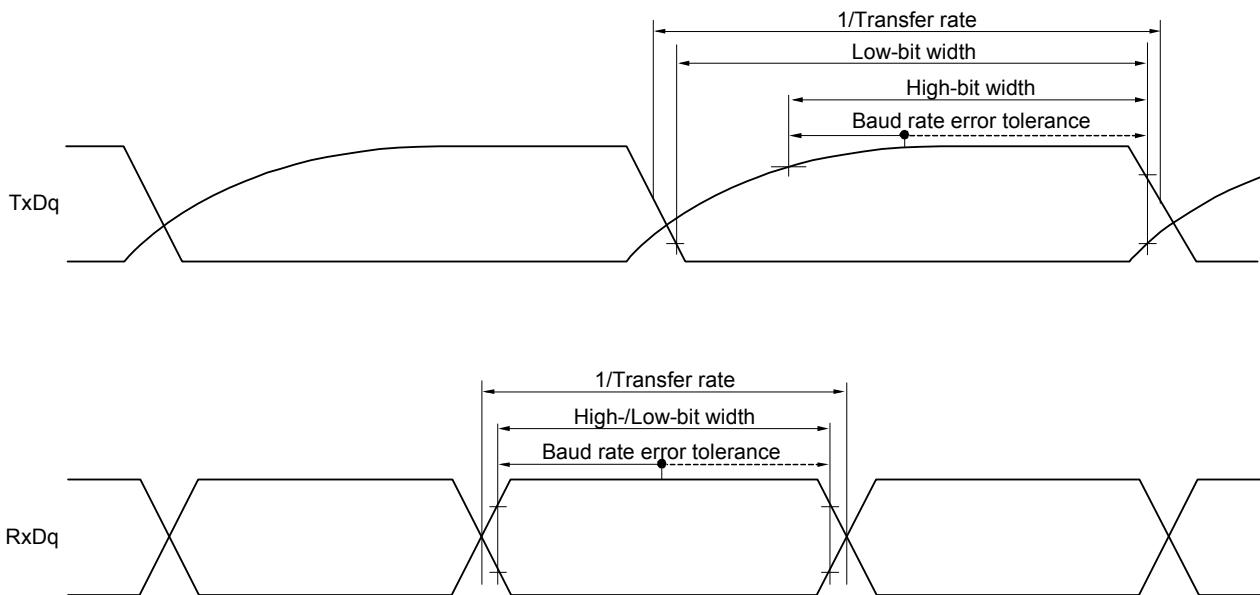
Note 1. Transfer rate in the SNOOZE mode is 4800 bps only.

However, the SNOOZE mode cannot be used when FRQSEL4 = 1.

Note 2. Use it with EV_{D0} ≥ V_b.**Note 3.** The following conditions are required for low voltage interface when EV_{D0} < V_{DD}.2.4 V ≤ EV_{D0} < 2.7 V: MAX. 2.6 Mbps1.8 V ≤ EV_{D0} < 2.4 V: MAX. 1.3 Mbps**Note 4.** The maximum operating frequencies of the CPU/peripheral hardware clock (f_{CLK}) are:HS (high-speed main) mode: 32 MHz (2.7 V ≤ V_{DD} ≤ 5.5 V)16 MHz (2.4 V ≤ V_{DD} ≤ 5.5 V)LS (low-speed main) mode: 8 MHz (1.8 V ≤ V_{DD} ≤ 5.5 V)LV (low-voltage main) mode: 4 MHz (1.6 V ≤ V_{DD} ≤ 5.5 V)**Caution** Select the TTL input buffer for the RxDq pin and the N-ch open drain output (V_{DD} tolerance (for the 30- to 52-pin products)/EV_{D0} tolerance (for the 64- to 100-pin products)) mode for the TxDq pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.**Remark 1.** V_b [V]: Communication line voltage**Remark 2.** q: UART number (q = 0 to 3), g: PIM and POM number (g = 0, 1, 5, 14)**Remark 3.** f_{MCK}: Serial array unit operation clock frequency

(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13)

Remark 4. UART2 cannot communicate at different potential when bit 1 (PIOR01) of peripheral I/O redirection register 0 (PIOR0) is 1.

UART mode connection diagram (during communication at different potential)**UART mode bit width (during communication at different potential) (reference)**

Remark 1. $R_b[\Omega]$: Communication line (TxDq) pull-up resistance,
 $C_b[F]$: Communication line (TxDq) load capacitance, $V_b[V]$: Communication line voltage

Remark 2. q: UART number (q = 0 to 3), g: PIM and POM number (g = 0, 1, 5, 14)

Remark 3. fmck: Serial array unit operation clock frequency

(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn)).

m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13))

Remark 4. UART2 cannot communicate at different potential when bit 1 (PIOR01) of peripheral I/O redirection register 0 (PIOR0) is 1.

(7) Communication at different potential (2.5 V, 3 V) (CSI mode) (master mode, SCKp... internal clock output, corresponding CSI00 only)

(TA = -40 to +85°C, 2.7 V ≤ EV_{DD0} = EV_{DD1} ≤ V_{DD} ≤ 5.5 V, V_{SS} = EV_{SS0} = EV_{SS1} = 0 V) (2/2)

Parameter	Symbol	Conditions	HS (high-speed main) mode		LS (low-speed main) mode		LV (low-voltage main) mode		Unit
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Slp setup time (to SCKp↓) Note 2	tsIK1	4.0 V ≤ EV _{DD0} ≤ 5.5 V, 2.7 V ≤ V _b ≤ 4.0 V, C _b = 20 pF, R _b = 1.4 kΩ	23		110		110		ns
		2.7 V ≤ EV _{DD0} < 4.0 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 20 pF, R _b = 2.7 kΩ	33		110		110		ns
Slp hold time (from SCKp↓) Note 2	tKSI1	4.0 V ≤ EV _{DD0} ≤ 5.5 V, 2.7 V ≤ V _b ≤ 4.0 V, C _b = 20 pF, R _b = 1.4 kΩ	10		10		10		ns
		2.7 V ≤ EV _{DD0} < 4.0 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 20 pF, R _b = 2.7 kΩ	10		10		10		ns
Delay time from SCKp↑ to SOp output Note 2	tKS01	4.0 V ≤ EV _{DD0} ≤ 5.5 V, 2.7 V ≤ V _b ≤ 4.0 V, C _b = 20 pF, R _b = 1.4 kΩ		10		10		10	ns
		2.7 V ≤ EV _{DD0} < 4.0 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 20 pF, R _b = 2.7 kΩ		10		10		10	ns

Note 1. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.

Note 2. When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

Caution Select the TTL input buffer for the Slp pin and the N-ch open drain output (V_{DD} tolerance (for the 30- to 52-pin products)/EV_{DD} tolerance (for the 64- to 100-pin products)) mode for the SOp pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

Remark 1. R_b[Ω]: Communication line (SCKp, SOp) pull-up resistance, C_b[F]: Communication line (SCKp, SOp) load capacitance, V_b[V]: Communication line voltage

Remark 2. p: CSI number (p = 00), m: Unit number (m = 0), n: Channel number (n = 0), g: PIM and POM number (g = 3, 5)

Remark 3. fmck: Serial array unit operation clock frequency

(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00))

Remark 4. This value is valid only when CSI00's peripheral I/O redirect function is not used.

(8) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (master mode, SCKp... internal clock output)

(TA = -40 to +85°C, 1.8 V ≤ EVDD0 = EVDD1 ≤ VDD ≤ 5.5 V, Vss = EVSS0 = EVSS1 = 0 V) (3/3)

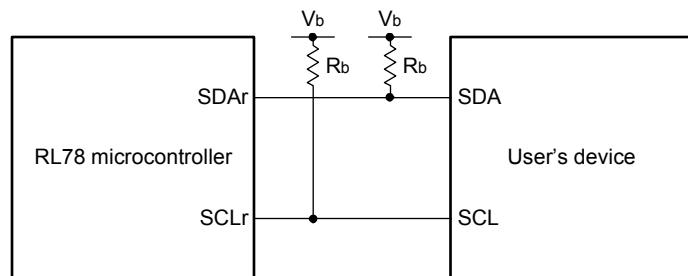
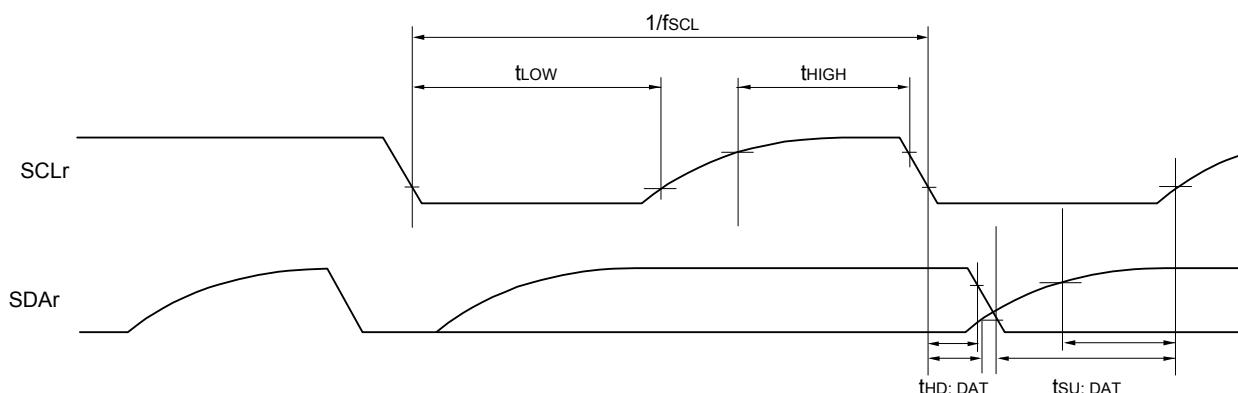
Parameter	Symbol	Conditions	HS (high-speed main mode)		LS (low-speed main mode)		LV (low-voltage main mode)		Unit
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Slp setup time (to SCKp↓) Note 1	tsIK1	4.0 V ≤ EVDD0 ≤ 5.5 V, 2.7 V ≤ Vb ≤ 4.0 V, Cb = 30 pF, Rb = 1.4 kΩ	44		110		110		ns
		2.7 V ≤ EVDD0 < 4.0 V, 2.3 V ≤ Vb ≤ 2.7 V, Cb = 30 pF, Rb = 2.7 kΩ	44		110		110		ns
		1.8 V ≤ EVDD0 < 3.3 V, 1.6 V ≤ Vb ≤ 2.0 V Note 2, Cb = 30 pF, Rb = 5.5 kΩ	110		110		110		ns
Slp hold time (from SCKp↓) Note 1	tksI1	4.0 V ≤ EVDD0 ≤ 5.5 V, 2.7 V ≤ Vb ≤ 4.0 V, Cb = 30 pF, Rb = 1.4 kΩ	19		19		19		ns
		2.7 V ≤ EVDD0 < 4.0 V, 2.3 V ≤ Vb ≤ 2.7 V, Cb = 30 pF, Rb = 2.7 kΩ	19		19		19		ns
		1.8 V ≤ EVDD0 < 3.3 V, 1.6 V ≤ Vb ≤ 2.0 V Note 2, Cb = 30 pF, Rb = 5.5 kΩ	19		19		19		ns
Delay time from SCKp↑ to SOp output Note 1	tksO1	4.0 V ≤ EVDD0 ≤ 5.5 V, 2.7 V ≤ Vb ≤ 4.0 V, Cb = 30 pF, Rb = 1.4 kΩ		25		25		25	ns
		2.7 V ≤ EVDD0 < 4.0 V, 2.3 V ≤ Vb ≤ 2.7 V, Cb = 30 pF, Rb = 2.7 kΩ		25		25		25	ns
		1.8 V ≤ EVDD0 < 3.3 V, 1.6 V ≤ Vb ≤ 2.0 V Note 2, Cb = 30 pF, Rb = 5.5 kΩ		25		25		25	ns

Note 1. When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

Note 2. Use it with EVDD0 ≥ Vb.

Caution Select the TTL input buffer for the Slp pin and the N-ch open drain output (VDD tolerance (for the 30- to 52-pin products)/EVDD tolerance (for the 64- to 100-pin products)) mode for the SOp pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg). For VIH and Vil, see the DC characteristics with TTL input buffer selected.

(Remarks are listed on the next page.)

Simplified I²C mode connection diagram (during communication at different potential)**Simplified I²C mode serial transfer timing (during communication at different potential)**

Remark 1. $R_b[\Omega]$: Communication line (SDAr, SCLR) pull-up resistance, $C_b[F]$: Communication line (SDAr, SCLR) load capacitance, $V_b[V]$: Communication line voltage

Remark 2. r: IIC number ($r = 00, 01, 10, 11, 20, 30, 31$), g: PIM, POM number ($g = 0, 1, 3$ to $5, 14$)

Remark 3. f_{MCK} : Serial array unit operation clock frequency

(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number ($m = 0, 1$), n: Channel number ($n = 0, 2$), mn = 00, 01, 02, 10, 12, 13)

(2) I²C fast mode(TA = -40 to +85°C, 1.6 V ≤ EV_{D0} = EV_{D1} ≤ V_{DD} ≤ 5.5 V, V_{SS} = EV_{S0} = EV_{S1} = 0 V)

Parameter	Symbol	Conditions		HS (high-speed main) mode		LS (low-speed main) mode		LV (low-voltage main) mode		Unit
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCLA0 clock frequency	fsCL	Fast mode: f _{CLK} ≥ 3.5 MHz	2.7 V ≤ EV _{D0} ≤ 5.5 V 1.8 V ≤ EV _{D0} ≤ 5.5 V	0	400	0	400	0	400	kHz
Setup time of restart condition	tsU: STA		2.7 V ≤ EV _{D0} ≤ 5.5 V 1.8 V ≤ EV _{D0} ≤ 5.5 V	0.6		0.6		0.6		μs
Hold time Note 1	t _{HD} : STA		2.7 V ≤ EV _{D0} ≤ 5.5 V 1.8 V ≤ EV _{D0} ≤ 5.5 V	0.6		0.6		0.6		μs
Hold time when SCLA0 = "L"	t _{LOW}		2.7 V ≤ EV _{D0} ≤ 5.5 V 1.8 V ≤ EV _{D0} ≤ 5.5 V	1.3		1.3		1.3		μs
Hold time when SCLA0 = "H"	t _{HIGH}		2.7 V ≤ EV _{D0} ≤ 5.5 V 1.8 V ≤ EV _{D0} ≤ 5.5 V	0.6		0.6		0.6		μs
Data setup time (reception)	tsU: DAT		2.7 V ≤ EV _{D0} ≤ 5.5 V 1.8 V ≤ EV _{D0} ≤ 5.5 V	100		100		100		ns
Data hold time (transmission)	t _{HD} : DAT	Note 2	2.7 V ≤ EV _{D0} ≤ 5.5 V 1.8 V ≤ EV _{D0} ≤ 5.5 V	0	0.9	0	0.9	0	0.9	μs
Setup time of stop condition	tsU: STO		2.7 V ≤ EV _{D0} ≤ 5.5 V 1.8 V ≤ EV _{D0} ≤ 5.5 V	0.6		0.6		0.6		μs
Bus-free time	t _{BUF}		2.7 V ≤ EV _{D0} ≤ 5.5 V 1.8 V ≤ EV _{D0} ≤ 5.5 V	1.3		1.3		1.3		μs

Note 1. The first clock pulse is generated after this period when the start/restart condition is detected.**Note 2.** The maximum value (MAX.) of t_{HD}: DAT is during normal transfer and a wait state is inserted in the ACK (acknowledge) timing.**Caution** The values in the above table are applied even when bit 2 (PIOR02) in the peripheral I/O redirection register 0 (PIOR0) is 1. At this time, the pin characteristics (I_{OH1}, I_{OL1}, V_{OH1}, V_{OL1}) must satisfy the values in the redirect destination.**Remark** The maximum value of C_b (communication line capacitance) and the value of R_b (communication line pull-up resistor) at that time in each mode are as follows.Fast mode: C_b = 320 pF, R_b = 1.1 kΩ

2.6.4 Comparator

(TA = -40 to +85°C, 1.6 V ≤ EV_{DD0} = EV_{DD1} ≤ V_{DD} ≤ 5.5 V, V_{SS} = EV_{VSS0} = EV_{VSS1} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Input voltage range	I _{Vref}			0		EV _{DD0} - 1.4	V
	I _{Vcmp}			-0.3		EV _{DD0} + 0.3	V
Output delay	t _d	V _{DD} = 3.0 V Input slew rate > 50 mV/μs	Comparator high-speed mode, standard mode			1.2	μs
			Comparator high-speed mode, window mode			2.0	μs
			Comparator low-speed mode, standard mode		3.0	5.0	μs
High-electric-potential reference voltage	V _{TW+}	Comparator high-speed mode, window mode			0.76 V _{DD}		V
Low-electric-potential ref- erence voltage	V _{TW-}	Comparator high-speed mode, window mode			0.24 V _{DD}		V
Operation stabilization wait time	t _{CMP}			100			μs
Internal reference voltage Note	V _{BGR}	2.4 V ≤ V _{DD} ≤ 5.5 V, HS (high-speed main) mode		1.38	1.45	1.50	V

Note Not usable in LS (low-speed main) mode, LV (low-voltage main) mode, sub-clock operation, or STOP mode.

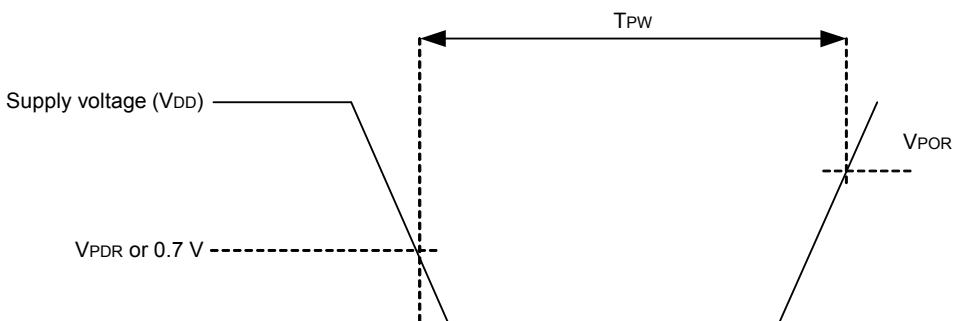
2.6.5 POR circuit characteristics

(TA = -40 to +85°C, V_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Power on/down reset threshold	V _{POR}	Voltage threshold on V _{DD} rising	1.47	1.51	1.55	V
	V _{PDR}	Voltage threshold on V _{DD} falling Note 1	1.46	1.50	1.54	V
Minimum pulse width Note 2	T _{PW}		300			μs

Note 1. However, when the operating voltage falls while the LVD is off, enter STOP mode, or enable the reset status using the external reset pin before the voltage falls below the operating voltage range shown in 2.4 AC Characteristics.

Note 2. Minimum time required for a POR reset when V_{DD} exceeds below V_{PDR}. This is also the minimum time required for a POR reset from when V_{DD} exceeds below 0.7 V to when V_{DD} exceeds V_{POR} while STOP mode is entered or the main system clock is stopped through setting bit 0 (HIOSTOP) and bit 7 (MSTOP) in the clock operation status control register (CSC).



3.3 DC Characteristics

3.3.1 Pin characteristics

(TA = -40 to +105°C, 2.4 V ≤ EVDD0 = EVDD1 ≤ VDD ≤ 5.5 V, Vss = EVSS0 = EVSS1 = 0 V)

Items	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output current, high Note 1	IOH1	Per pin for P00 to P06, P10 to P17, P30, P31, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P100 to P102, P110, P111, P120, P130, P140 to P147	2.4 V ≤ EVDD0 ≤ 5.5 V			-3.0 Note 2	mA
		Total of P00 to P04, P40 to P47, P102, P120, P130, P140 to P145 (When duty ≤ 70% Note 3)	4.0 V ≤ EVDD0 ≤ 5.5 V			-30.0	mA
			2.7 V ≤ EVDD0 < 4.0 V			-10.0	mA
			2.4 V ≤ EVDD0 < 2.7 V			-5.0	mA
		Total of P05, P06, P10 to P17, P30, P31, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P100, P101, P110, P111, P146, P147 (When duty ≤ 70% Note 3)	4.0 V ≤ EVDD0 ≤ 5.5 V			-30.0	mA
			2.7 V ≤ EVDD0 < 4.0 V			-19.0	mA
			2.4 V ≤ EVDD0 < 2.7 V			-10.0	mA
		Total of all pins (When duty ≤ 70% Note 3)	2.4 V ≤ EVDD0 ≤ 5.5 V			-60.0	mA
	IOH2	Per pin for P20 to P27, P150 to P156	2.4 V ≤ VDD ≤ 5.5 V			-0.1 Note 2	mA
		Total of all pins (When duty ≤ 70% Note 3)	2.4 V ≤ VDD ≤ 5.5 V			-1.5	mA

Note 1. Value of current at which the device operation is guaranteed even if the current flows from the EVDD0, EVDD1, VDD pins to an output pin.

Note 2. Do not exceed the total current value.

Note 3. Specification under conditions where the duty factor ≤ 70%.

The output current value that has changed to the duty factor > 70% the duty ratio can be calculated with the following expression (when changing the duty factor from 70% to n%).

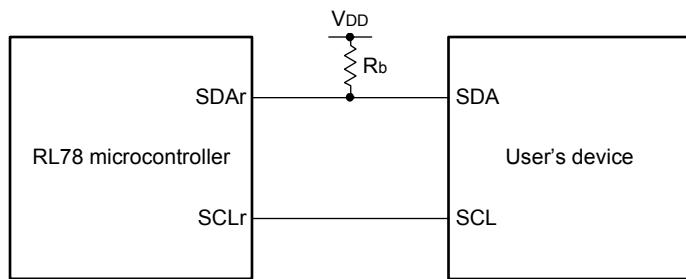
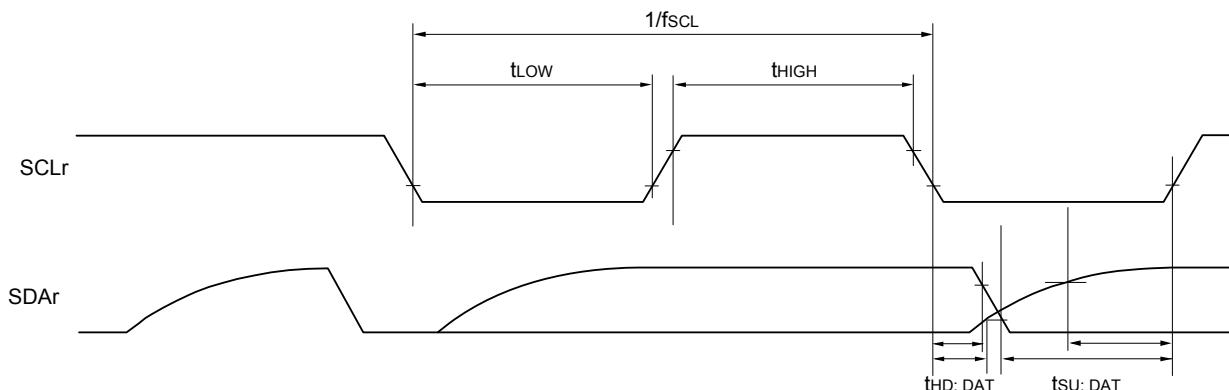
- Total output current of pins = $(IOH \times 0.7)/(n \times 0.01)$
 <Example> Where n = 80% and IOH = -10.0 mA
 $\text{Total output current of pins} = (-10.0 \times 0.7)/(80 \times 0.01) \approx -8.7 \text{ mA}$

However, the current that is allowed to flow into one pin does not vary depending on the duty factor.

A current higher than the absolute maximum rating must not flow into one pin.

Caution P00, P02 to P04, P10, P11, P13 to P15, P17, P30, P43 to P45, P50 to P55, P71, P74, P80 to P82, and P142 to P144 do not output high level in N-ch open-drain mode.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

Simplified I²C mode connection diagram (during communication at same potential)**Simplified I²C mode serial transfer timing (during communication at same potential)**

Remark 1. $R_b[\Omega]$: Communication line (SDAr) pull-up resistance, $C_b[F]$: Communication line (SDAr, SCLr) load capacitance

Remark 2. r: IIC number ($r = 00, 01, 10, 11, 20, 21, 30, 31$), g: PIM number ($g = 0, 1, 3$ to $5, 14$),

h: POM number ($h = 0, 1, 3$ to $5, 7, 14$)

Remark 3. f_{MCK} : Serial array unit operation clock frequency

(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number ($m = 0, 1$),

n: Channel number ($n = 0$ to 3), mn = 00 to 03, 10 to 13)

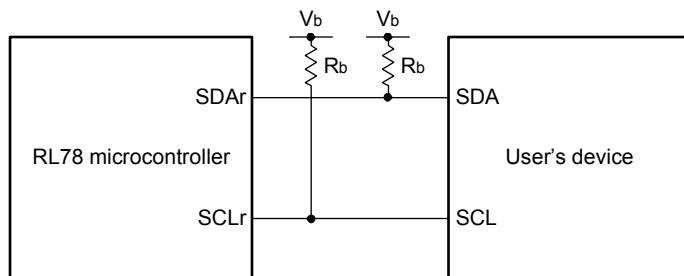
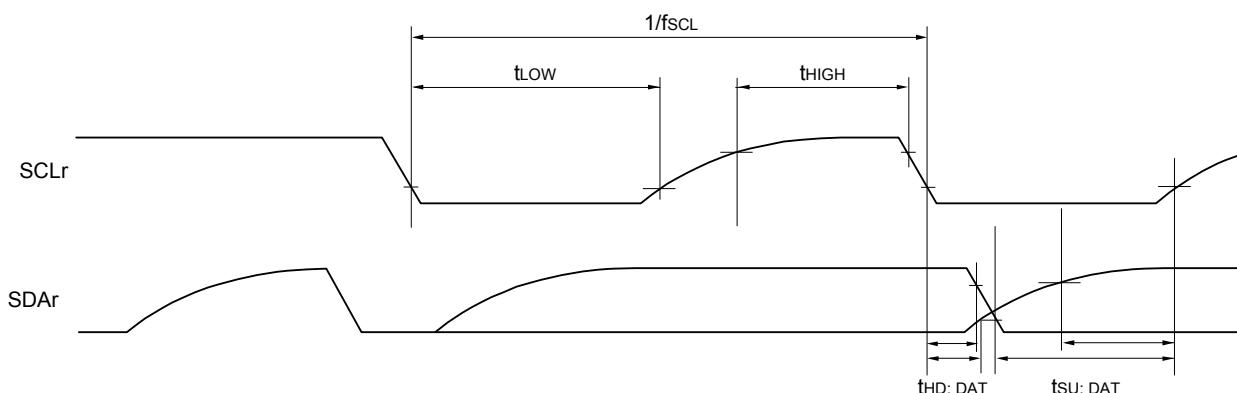
(6) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (master mode, SCKp... internal clock output)

(TA = -40 to +105°C, 2.4 V ≤ EV_{DD0} = EV_{DD1} ≤ V_{DD} ≤ 5.5 V, V_{SS} = EV_{VSS0} = EV_{VSS1} = 0 V)

Parameter	Symbol	Conditions	HS (high-speed main) mode		Unit
			MIN.	MAX.	
SCKp cycle time	t _{KCY1}	t _{KCY1} ≥ 4/f _{CLK}	4.0 V ≤ EV _{DD0} ≤ 5.5 V, 2.7 V ≤ V _b ≤ 4.0 V, C _b = 30 pF, R _b = 1.4 kΩ	600	ns
			2.7 V ≤ EV _{DD0} < 4.0 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 30 pF, R _b = 2.7 kΩ	1000	ns
			2.4 V ≤ EV _{DD0} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V, C _b = 30 pF, R _b = 5.5 kΩ	2300	ns
SCKp high-level width	t _{KH1}	4.0 V ≤ EV _{DD0} ≤ 5.5 V, 2.7 V ≤ V _b ≤ 4.0 V, C _b = 30 pF, R _b = 1.4 kΩ	t _{KCY1/2} - 150		ns
		2.7 V ≤ EV _{DD0} < 4.0 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 30 pF, R _b = 2.7 kΩ	t _{KCY1/2} - 340		ns
		2.4 V ≤ EV _{DD0} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V, C _b = 30 pF, R _b = 5.5 kΩ	t _{KCY1/2} - 916		ns
SCKp low-level width	t _{KL1}	4.0 V ≤ EV _{DD0} ≤ 5.5 V, 2.7 V ≤ V _b ≤ 4.0 V, C _b = 30 pF, R _b = 1.4 kΩ	t _{KCY1/2} - 24		ns
		2.7 V ≤ EV _{DD0} < 4.0 V, 2.3 V ≤ V _b ≤ 2.7 V, C _b = 30 pF, R _b = 2.7 kΩ	t _{KCY1/2} - 36		ns
		2.4 V ≤ EV _{DD0} < 3.3 V, 1.6 V ≤ V _b ≤ 2.0 V, C _b = 30 pF, R _b = 5.5 kΩ	t _{KCY1/2} - 100		ns

Caution Select the TTL input buffer for the S_lp pin and the N-ch open drain output (V_{DD} tolerance (for the 30- to 52-pin products)/EV_{DD} tolerance (for the 64- to 100-pin products)) mode for the SO_p pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

(Remarks are listed two pages after the next page.)

Simplified I²C mode connection diagram (during communication at different potential)**Simplified I²C mode serial transfer timing (during communication at different potential)**

Remark 1. $R_b[\Omega]$: Communication line (SDAr, SCLR) pull-up resistance, $C_b[F]$: Communication line (SDAr, SCLR) load capacitance, $V_b[V]$: Communication line voltage

Remark 2. r: IIC number ($r = 00, 01, 10, 11, 20, 30, 31$), g: PIM, POM number ($g = 0, 1, 3$ to $5, 14$)

Remark 3. f_{MCK} : Serial array unit operation clock frequency

(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number ($m = 0, 1$), n: Channel number ($n = 0, 2$), mn = 00, 01, 02, 10, 12, 13)

3.6.4 Comparator

(TA = -40 to +105°C, 2.4 V ≤ EV_{DD0} = EV_{DD1} ≤ V_{DD} ≤ 5.5 V, V_{SS} = EV_{SS0} = EV_{SS1} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Input voltage range	I _{VREF}			0		EV _{DD0} - 1.4	V
	I _{VCOMP}			-0.3		EV _{DD0} + 0.3	V
Output delay	t _D	V _{DD} = 3.0 V Input slew rate > 50 mV/μs	Comparator high-speed mode, standard mode			1.2	μs
			Comparator high-speed mode, window mode			2.0	μs
			Comparator low-speed mode, standard mode		3.0	5.0	μs
High-electric-potential reference voltage	V _{TW+}	Comparator high-speed mode, window mode			0.76 V _{DD}		V
Low-electric-potential ref- erence voltage	V _{TW-}	Comparator high-speed mode, window mode			0.24 V _{DD}		V
Operation stabilization wait time	t _{CMP}			100			μs
Internal reference voltage Note	V _{BGR}	2.4 V ≤ V _{DD} ≤ 5.5 V, HS (high-speed main) mode		1.38	1.45	1.50	V

Note Not usable in sub-clock operation or STOP mode.

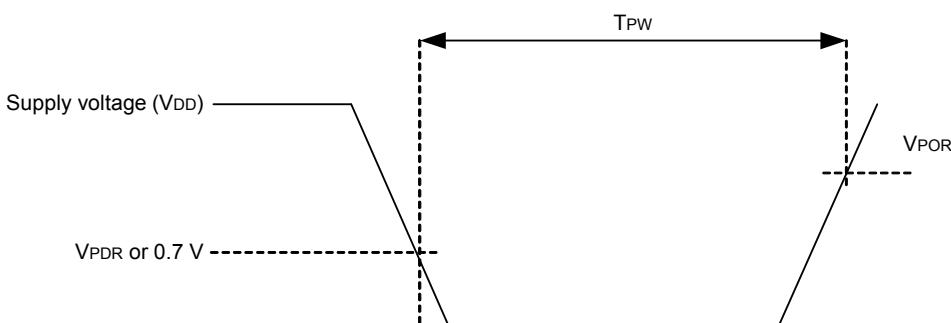
3.6.5 POR circuit characteristics

(TA = -40 to +105°C, V_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Power on/down reset threshold	V _{POR}	Voltage threshold on V _{DD} rising	1.45	1.51	1.57	V
	V _{PDR}	Voltage threshold on V _{DD} falling Note 1	1.44	1.50	1.56	V
Minimum pulse width Note 2	T _{PW}		300			μs

Note 1. However, when the operating voltage falls while the LVD is off, enter STOP mode, or enable the reset status using the external reset pin before the voltage falls below the operating voltage range shown in 3.4 AC Characteristics.

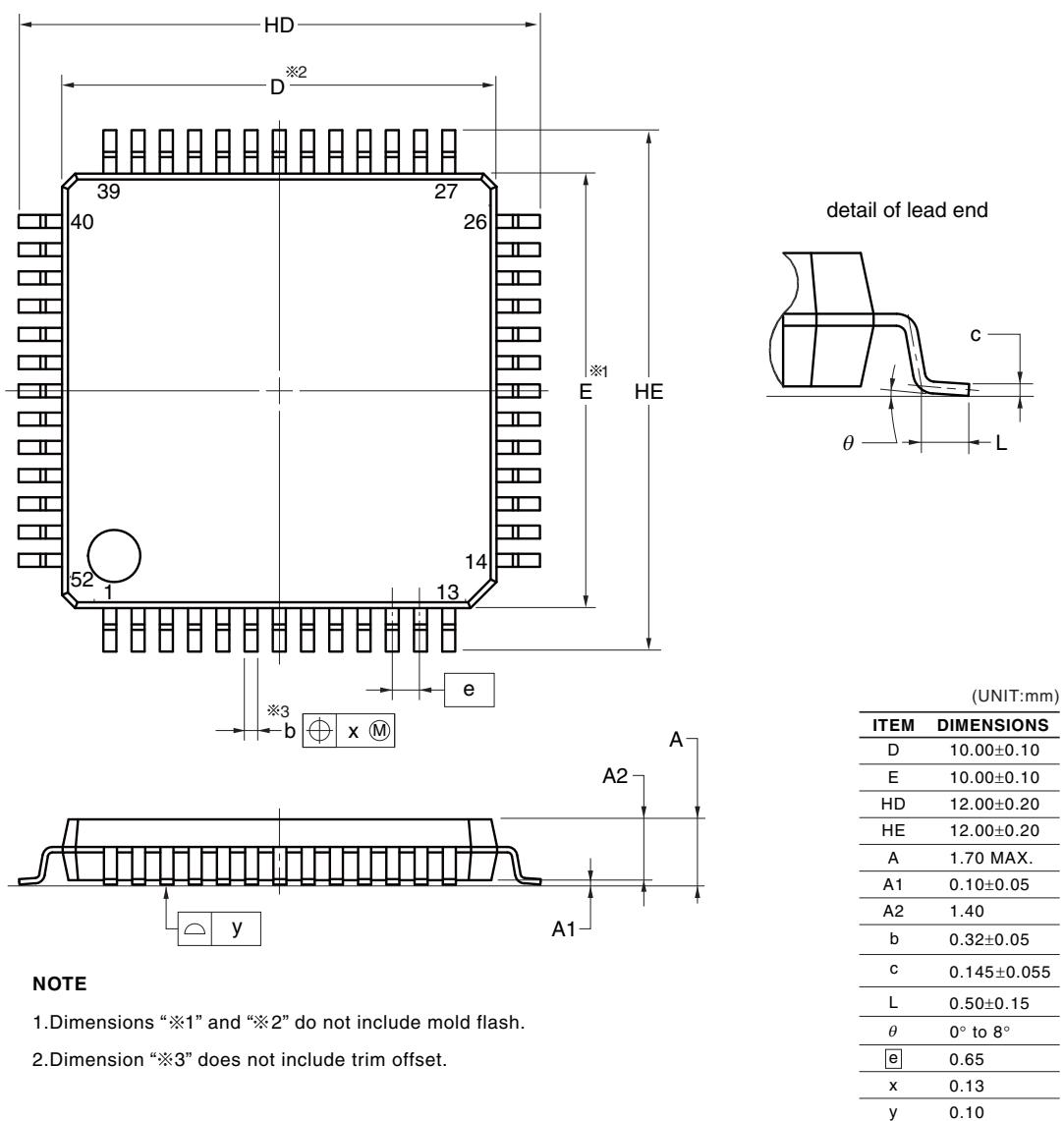
Note 2. Minimum time required for a POR reset when V_{DD} exceeds below V_{PDR}. This is also the minimum time required for a POR reset from when V_{DD} exceeds below 0.7 V to when V_{DD} exceeds V_{POR} while STOP mode is entered or the main system clock is stopped through setting bit 0 (HIOSTOP) and bit 7 (MSTOP) in the clock operation status control register (CSC).



4.7 52-pin products

R5F104JCAFA, R5F104JDAFA, R5F104JEAF, R5F104JFAFA, R5F104JGAF, R5F104JHAF, R5F104JJAF, R5F104JCDFA, R5F104JDDFA, R5F104JEDFA, R5F104JFDFA, R5F104JGDFA, R5F104JHDFA, R5F104JJDFA, R5F104JCGFA, R5F104JDGFA, R5F104JEGFA, R5F104JFGFA, R5F104JGGFA, R5F104JHGFA, R5F104JJGFA

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-LQFP52-10x10-0.65	PLQP0052JA-A	P52GB-65-GBS-1	0.3



© 2012 Renesas Electronics Corporation. All rights reserved.